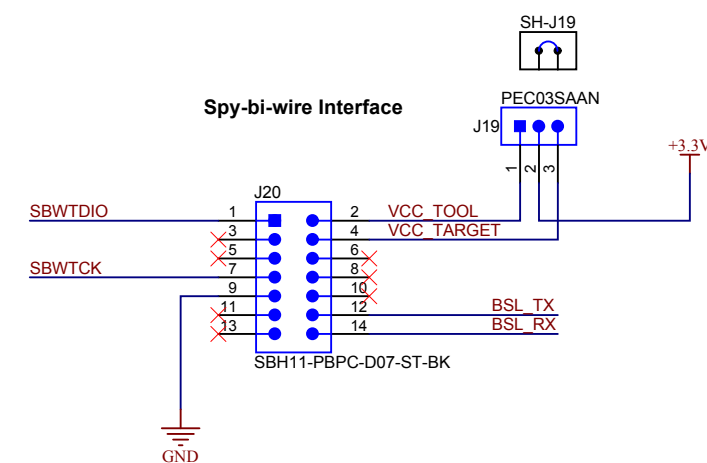
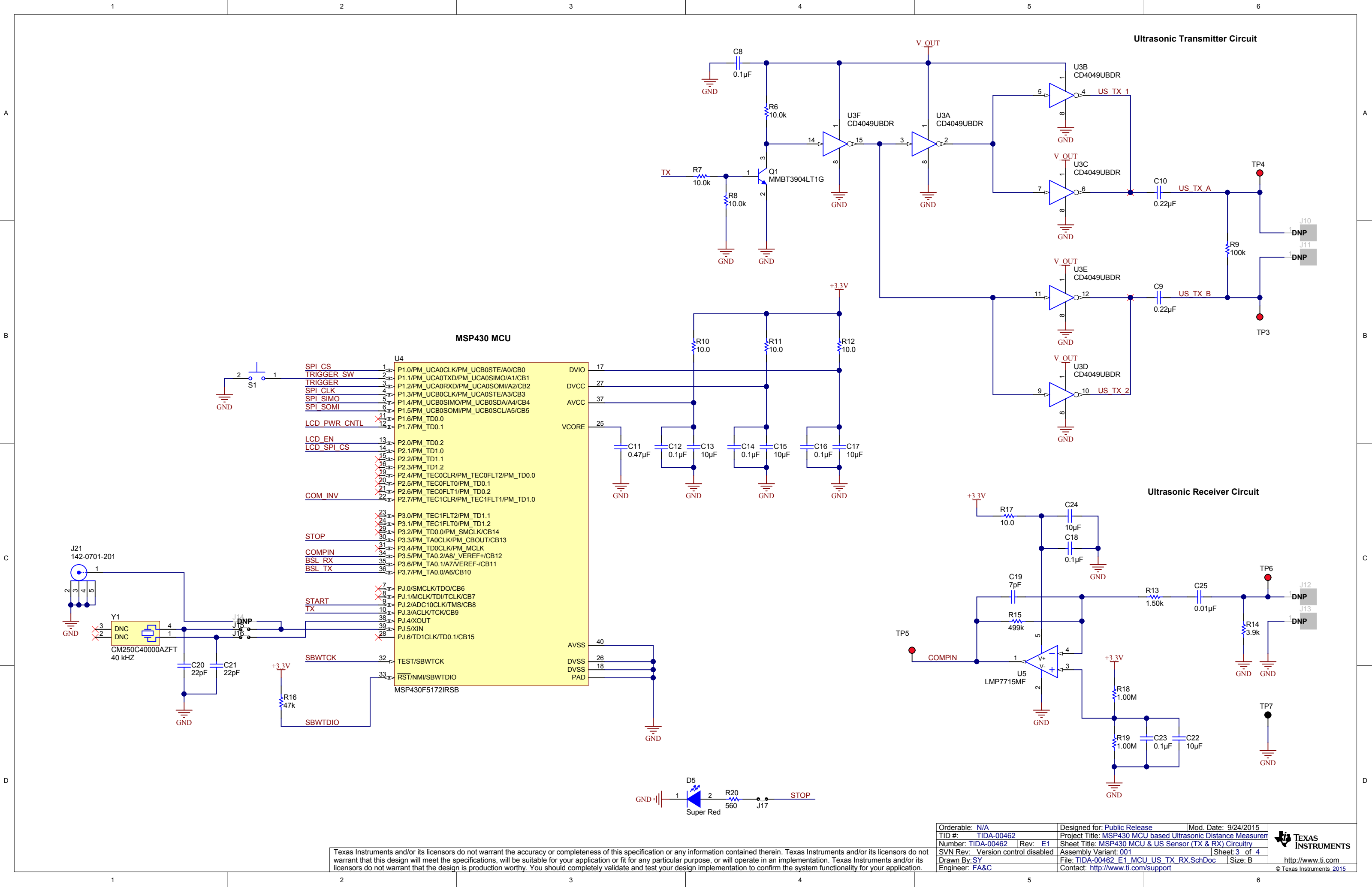


J7 TO BP PIN MAPPING	
BP-40 <-- J7-1	J7-2 --> BP-20
BP-39 <-- J7-3	J7-4 --> BP-19
BP-38 <-- J7-5	J7-6 --> BP-18
BP-37 <-- J7-7	J7-8 --> BP-17
BP-36 <-- J7-9	J7-10 --> BP-16
BP-35 <-- J7-11	J7-12 --> BP-15
BP-34 <-- J7-13	J7-14 --> BP-14
BP-33 <-- J7-15	J7-16 --> BP-13
BP-32 <-- J7-17	J7-18 --> BP-12
BP-31 <-- J7-19	J7-20 --> BP-11

Note for user:

1. Ultrasonic measurement is issued either manually (TRIGGER_SW) or via Launchpad (TRIGGER signal).
2. BoosterPack execute the state machine which triggers the TX signal to the ultrasound transducers.
3. When the ultrasound wave is received it is amplified and fed to the COMPIN.
4. If the echo signal is valid signal STOP LED lights up and same STOP signal is also fed to LaunchPad.





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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/24/2015
TID #: TIDA-00462	Project Title: MSP430 MCU based Ultrasonic Distance Measurement	
Number: TIDA-00462	Rev: E1	Sheet Title: MSP430 MCU & US Sensor (TX & RX) Circuitry
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By: SY	File: TIDA-00462_E1_MCU_US_TX_RX.SchDoc	Size: B
Engineer: FA&C	Contact: http://www.ti.com/support	http://www.ti.com

DNP

FID1

DNP

FID2

DNP

FID3

PCB Number: TIDA-00462

PCB Rev: E1

PCB

LOGO

Texas Instruments

PCB

LOGO

ESD Susceptible

Label Table	
Variant	Label Text
001	TIDA-00462 REV: E1

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A		Designed for: Public Release	Mod. Date: 9/1/2015
TID #: TIDA-00462		Project Title: MSP430 MCU based Ultrasonic Distance Measuren	
Number: TIDA-00462	Rev: E1	Sheet Title: Hardware	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 4 of 4
Drawn By: SY		File: TIDA-00462_E1_TID_Hardware.SchDoc	Size: B
Engineer: FA&C		Contact: http://www.ti.com/support	